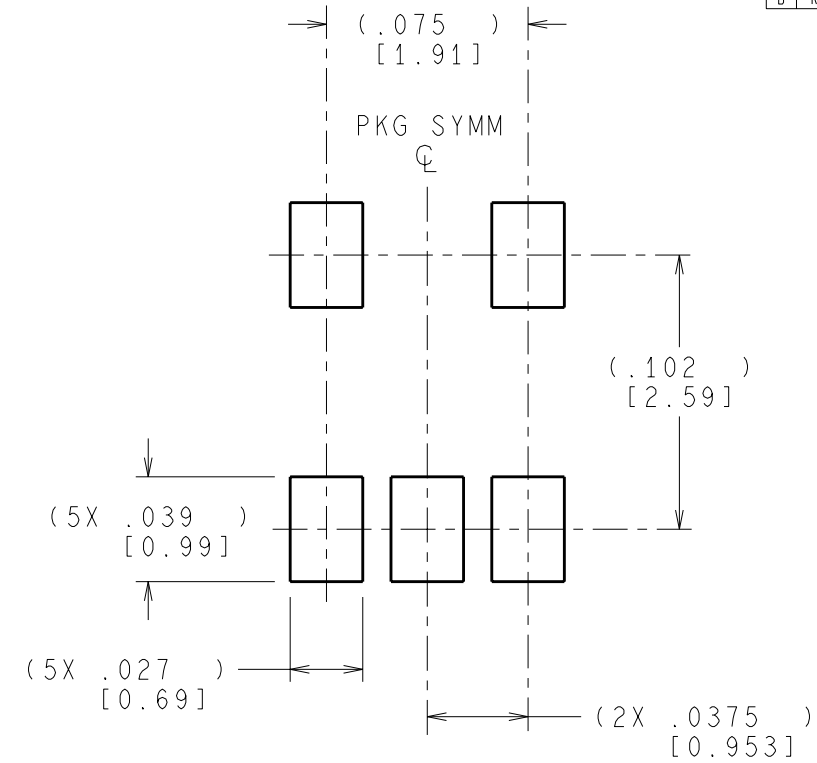
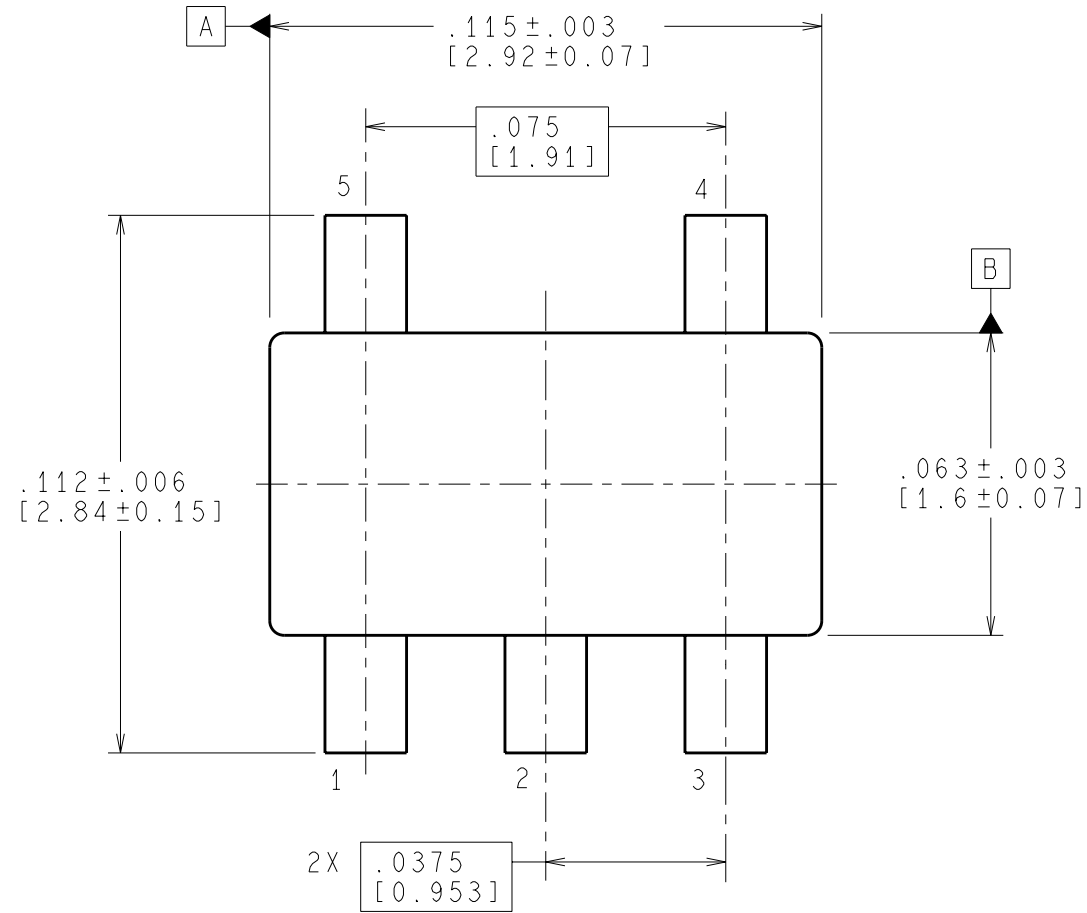
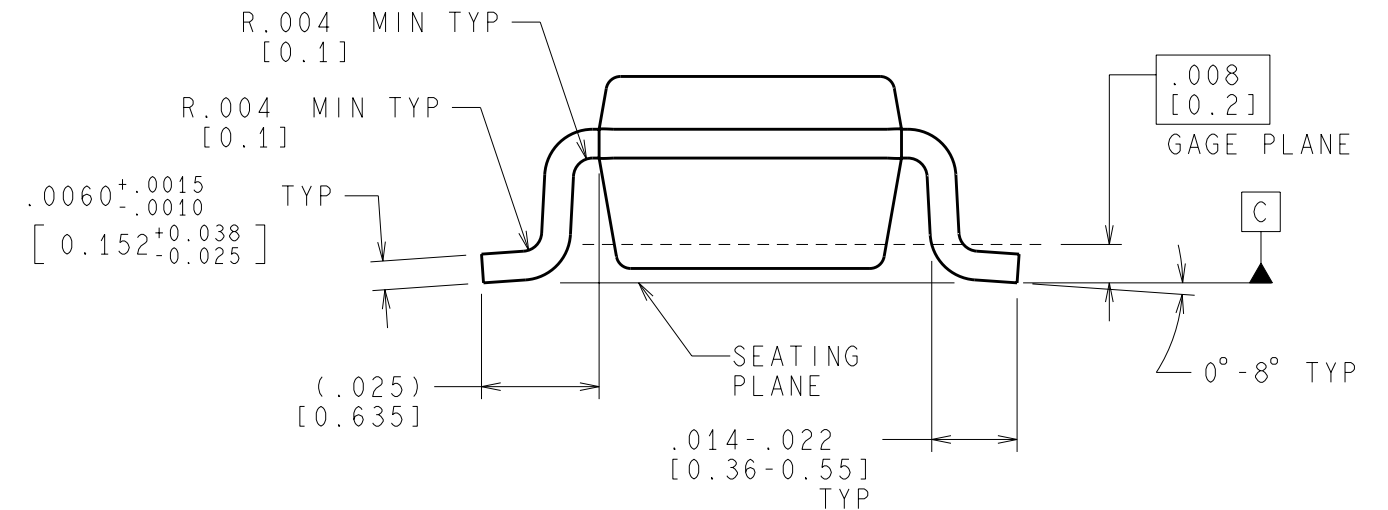
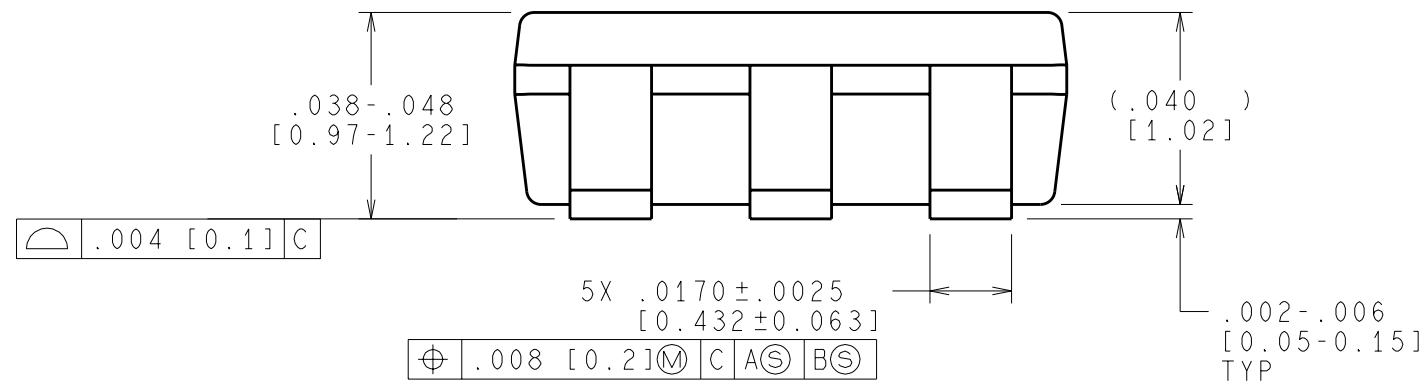


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12343	01/07/2000	TL/RW
B	REVISE NOTE 1; CHANGE DWG FORMAT TO B SIZE	983	03/27/2003	TL/RW



**LAND PATTERN RECOMMENDATION**



**CONTROLLING DIMENSION IS INCH  
VALUES IN [ ] ARE MILLIMETERS**

NOTES: UNLESS OTHERWISE SPECIFIED

1. FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE ([www.national.com](http://www.national.com)).

2. REFERENCE JEDEC REGISTRATION MO-178, VARIATION AA.

APPROVALS	DATE	National Semiconductor	
DRAWN LEQUANG	01/07/2000	2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DTG. CHK. MARTA SUCHY	03/27/2003	MOLDED SOT-23, .115x.063x.040 in BODY, 5 LD, .0375 in PITCH	
ENGR. CHK. RANDALL WALBERG	03/27/2003		
PROJECTION	SCALE	SIZE	DRAWING NUMBER
	NTS	B	(SC)MKT-MF05A
INCH (MM)	FORMERLY: N/A		REV B